



Product Specification

Product:	Dielectric Paste
Part Number:	07H-1124

Application Scope :

This paste is suitable for surface encapsulation of 430 stainless steel heating thick-film circuits.

Usage Conditions :

Substrate	430 stainless steel
Usage Method	Printing, 150-200 mesh
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (the baking temperature should not exceed 300°C, and the baking time may be adjusted based on actual conditions).
Firing Condition	The sintering temperature is 850°C (recommended value) and the sintering time is 10 minutes.
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	$\leq 8\mu\text{m}$	FOG test
2 Viscosity	100~200Pa.s	Boli Fei viscometer, rotor SC4-14/6R), 10 rpm, $25\pm 1^\circ\text{C}$
3 Appearance	Blue	

2. Characteristics After Curing :

Under sintering condition 1, the thickness of the film layer is not less than 80um.



Characteristics		Standard	Test Method And Conditions
4	Appearance	Compact and dense	Visual
5	Capacitance of unit	$\leq 3.0\text{PF/mm}^2$	KT2618 type
6	Wastage of insulation	<1%	KT2618 type
7	Insulation Resistance	$>10^9\Omega$ (500VDC, 25°C)	RCJ-3 type
8	Breakdown Voltage	$>2000\text{VAC}$, 25°C	CS2673A type
9	Dielectric Constant(ϵ)	9~15	Calculation

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.